CLAIMS

1. An integrated circuit for a fluidic die comprising:

an address bus to communicate a set of addresses;

a first portion of memory elements to receive a first set of address bits representative of a first portion of an address of the set of addresses;

a second portion of memory elements to receive a second set of address bits representative of a remaining portion of the address of the set of addresses;

a first group of die configuration functions including a first address driver to drive the first portion of the address of the set of addresses on the address bus using the first set of address bits stored by the first portion of memory elements;

a second group of die configuration functions including a second address driver to drive the remaining portion of the address of the set of addresses on the address bus using the second set of address bits stored by the second portion of memory elements; and

an array of fluid actuating devices addressable by the set of addresses communicated via the address bus.

2. The integrated circuit of claim 1, the first portion and second portion together representing the address of the set of addresses.

3. The integrated circuit of claims 1 or 2, the array of fluid actuating devices arranged as a column of fluid actuating devices extending in a longitudinal direction between the first and second groups of die configuration functions.

4. The integrated circuit of any of claims 1-3, including:

an array of memory elements including:

the first portion of memory elements corresponding to the first group of die configuration functions;

the second portion of memory elements corresponding to the second group of die configuration functions; and

a third portion of memory elements corresponding to the array of fluid actuating devices;

the array of memory elements to serially load data segments such that upon completion of loading a data segment, the first portion of memory elements stores the first set of address bits representing the first portion of the address of the set of addresses, and the second portion of memory elements stores the second set of address bits representing the remaining portion of the address of the set of addresses.

5. The integrated circuit of claim 4, the array of memory elements comprising a chain of memory elements to function as a serial-to-parallel data converter with the first portion of memory elements disposed proximate to the first group of die configuration functions, the second portion of memory elements disposed proximate to the second group of die configuration functions, and the third portion of memory elements extending between the first and second portions of memory elements and disposed proximate to the array of fluid actuating devices.

6. The integrated circuit of any of claims 1-5, in addition to first and second address drivers, the first and second die configuration functions respectively further comprising a fire pulse control function and a sensor configuration function.

7. A fluidic die comprising:

a column of fluid actuating devices addressable by a set of addresses;

a first address driver to provide a first portion of an address of the set of addresses based on a first set of address bits;

a second address driver to provide a remaining portion of the address of the set of addresses based on a second set of address bits; and

an array of memory elements including a first portion of memory elements corresponding to the first address driver, and a second portion of memory elements corresponding to the second address driver, the array of memory elements to serially load data segments such that upon completion of loading a data segment the memory elements of the first portion store the first set of address bits and the memory elements of the second portion store the second set of address bits.

8. The fluidic die of claim 7, the array of memory elements including a third portion of memory elements corresponding to the column of fluid actuating devices.

9. The fluidic die of claim 7 or 8, the column of fluid actuating devices extending longitudinally between the first address driver and second address driver.

10. The fluidic die of any of claims 8, the fluid actuating devices of the column of fluid actuating devices arranged to form a number of primitives, the fluid actuating devices of each primitive addressable by the set of addresses with each fluid actuating device corresponding to a different one of the addresses of the set of addresses, where each memory element of the third portion of memory elements corresponds to a different one of the primitives.

11. The fluidic die of claims 8 or 10, the array of memory elements comprising a chain of memory elements to function as a serial-to-parallel data converter, the chain of memory elements extending in parallel with the column of fluid actuating devices with the first portion of memory elements disposed proximate to the first address driver, the second portion of memory elements disposed proximate to the second address driver, and the third portion of memory elements extending between the first and second portions of memory elements and disposed proximate to the column of fluid actuating devices.

12. An integrated circuit for fluid ejection comprising:

a series of memory elements including:

a first portion of memory elements corresponding to a first group of die configuration functions;

a second portion corresponding to a second group of die configuration functions; and

a third portion corresponding to fluid actuating devices, the third portion extending longitudinally between the first and second portions, the series of memory elements to serially load data segments comprising a number of data bits such that upon completion of loading of a data segment, the first portion of memory elements stores data bits for the first group of die configuration functions, the second portion of the memory elements stores data bits for the second group of die configuration functions, and the third portion of memory elements store data bits for the fluid actuating devices.

13. The integrated circuit of claim 12, the fluid actuating devices disposed between the first and second groups of die configuration functions.